

TITLE: METHODS FOR DESIGNING BOND PAD REROUTING
ELEMENTS FOR USE IN STACKED SEMICONDUCTOR DEVICE
ASSEMBLIES AND FOR ASSEMBLING SEMICONDUCTOR DEVICES

Inventor: Corisis et. Al.

Docket No.: 2269-4814.1US

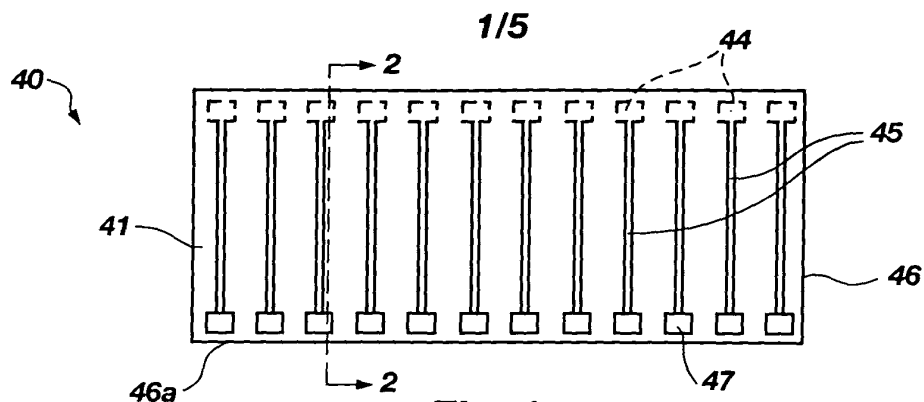


Fig. 1

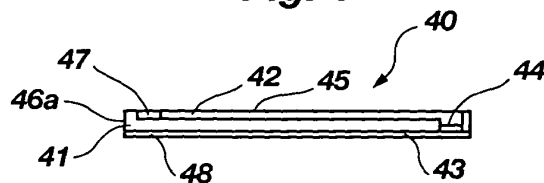


Fig. 2

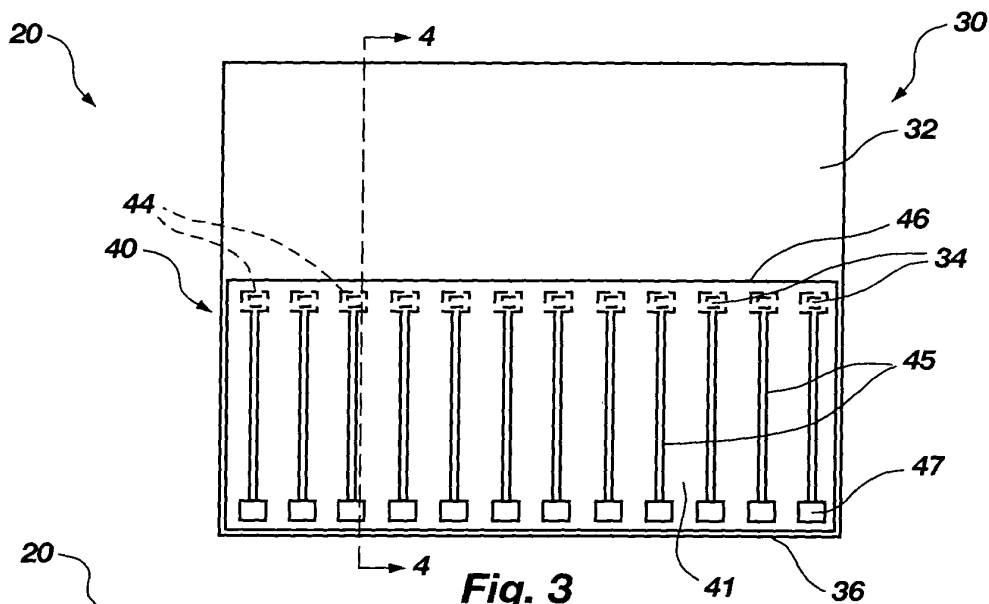


Fig. 3

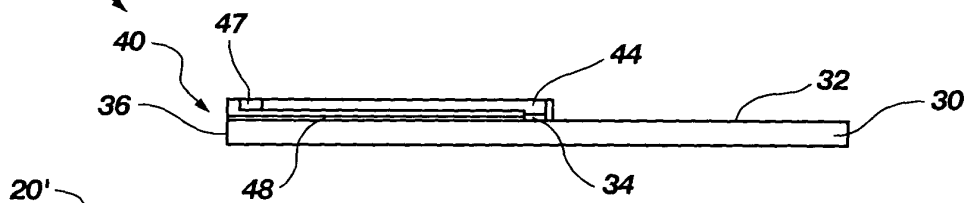


Fig. 4

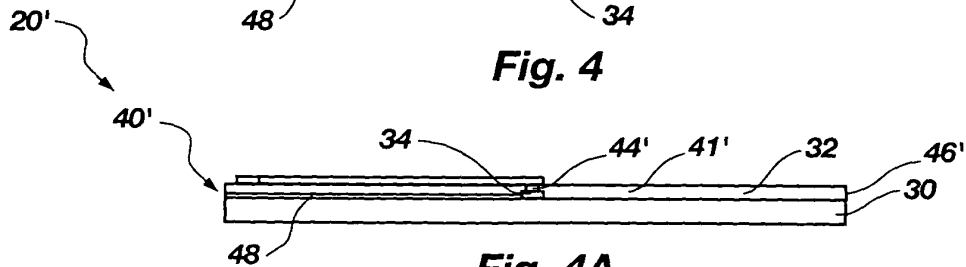


Fig. 4A



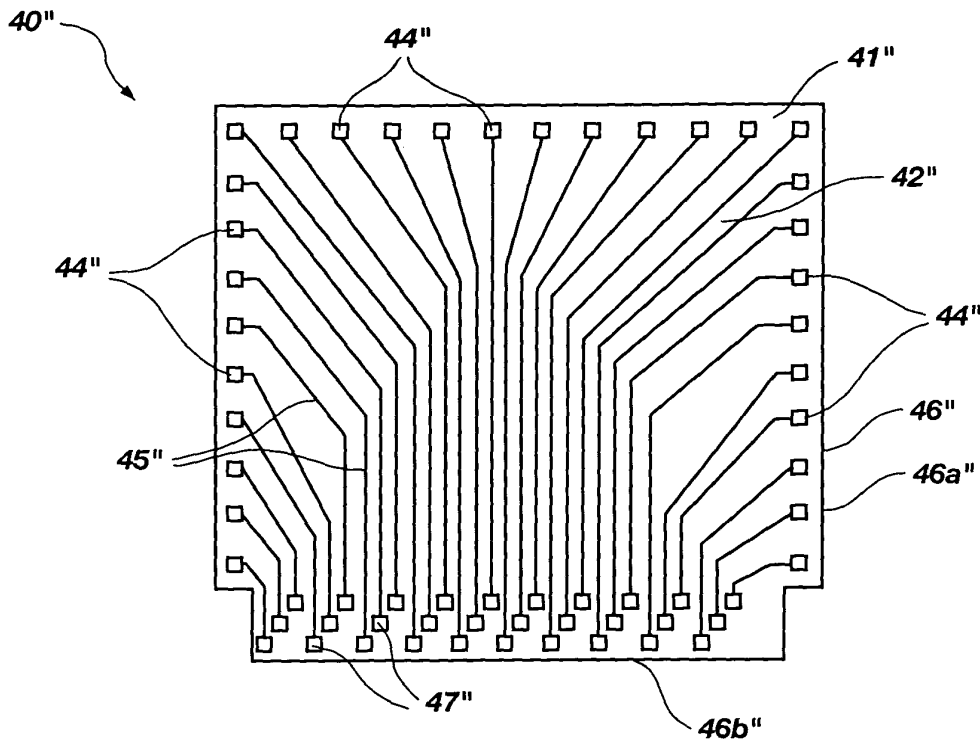


Fig. 9

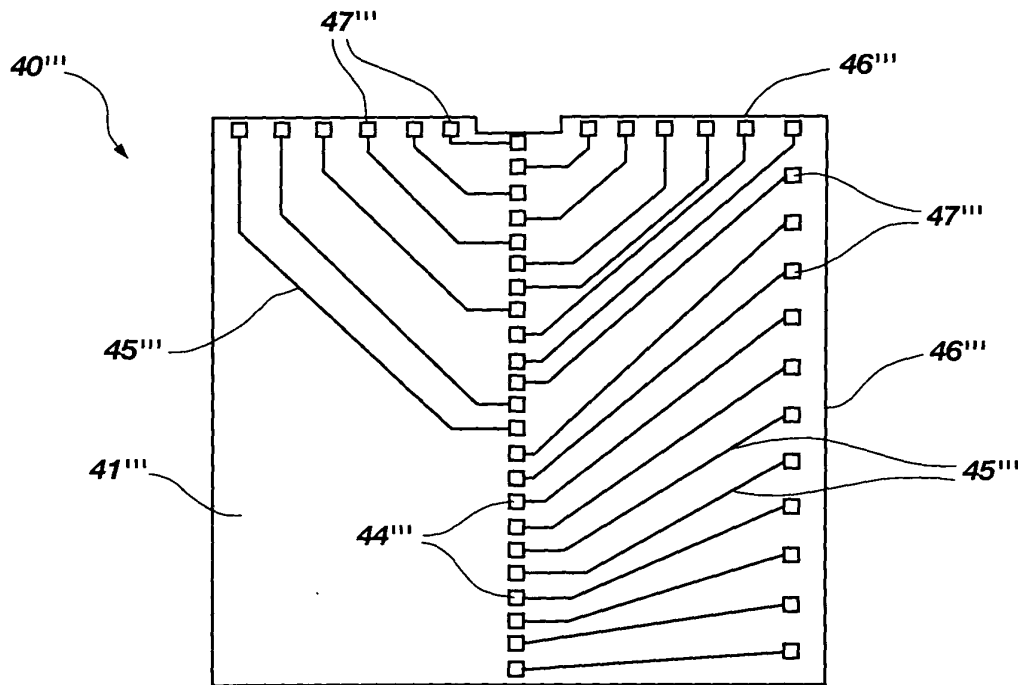


Fig. 10

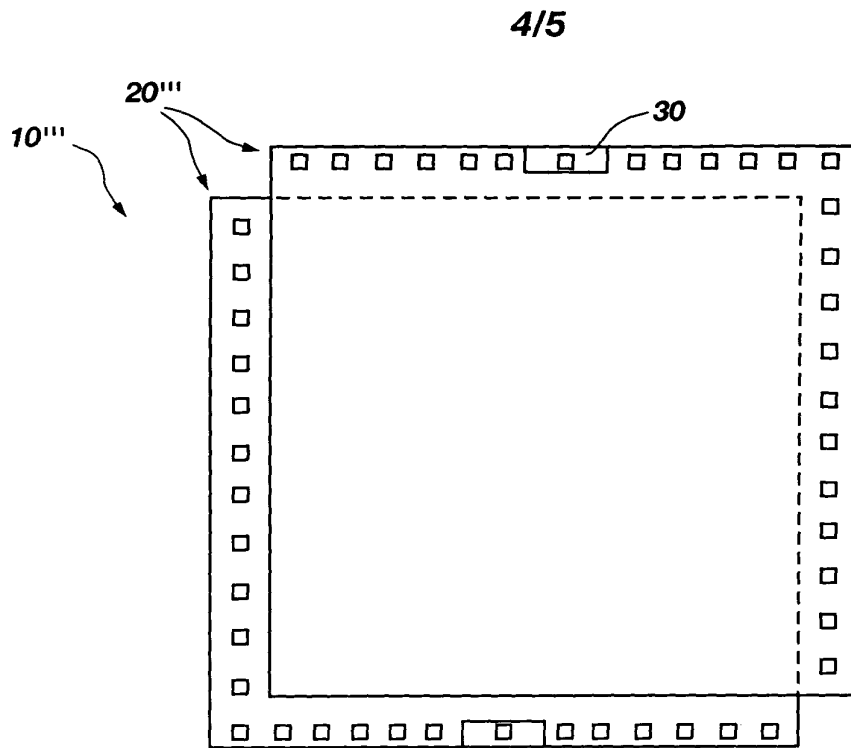


Fig. 11

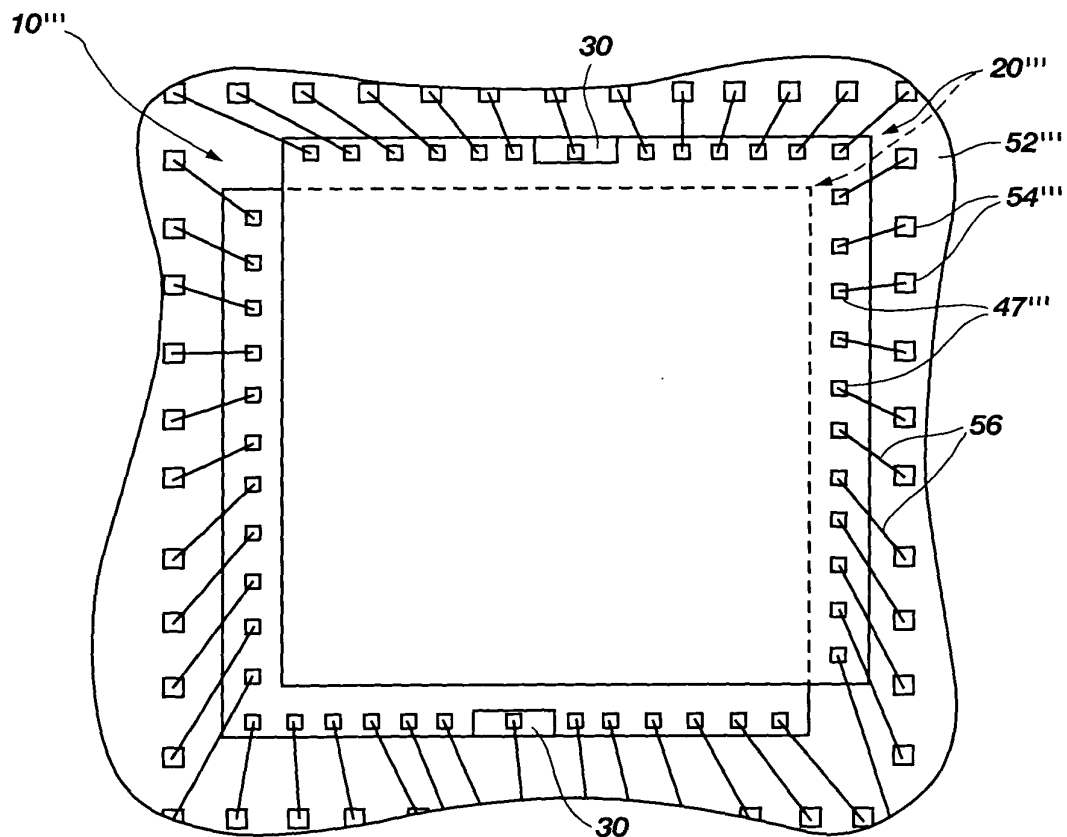


Fig. 12

TITLE: METHODS FOR DESIGNING BOND PAD REROUTING
ELEMENTS FOR USE IN STACKED SEMICONDUCTOR DEVICE
ASSEMBLIES AND FOR ASSEMBLING SEMICONDUCTOR DEVICES

Inventor: Corisis et. Al.
Docket No.: 2269-4814.1US

5/5

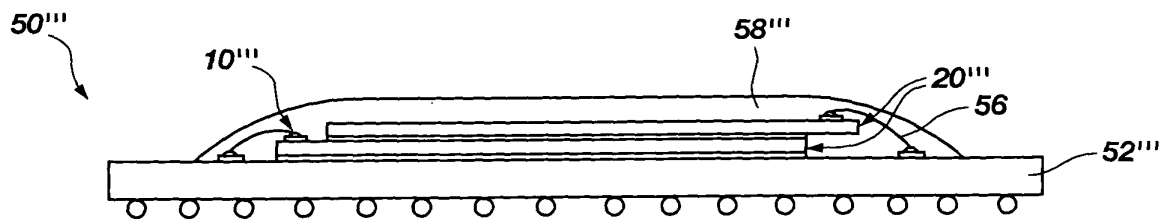


Fig. 13